

## SURFACE MOUNT GLASS PASSIVATED RECTIFIERS

REVERSE VOLTAGE - 50 to 1000Volts  
POWER DISSIPATION - 3.0 Amperes

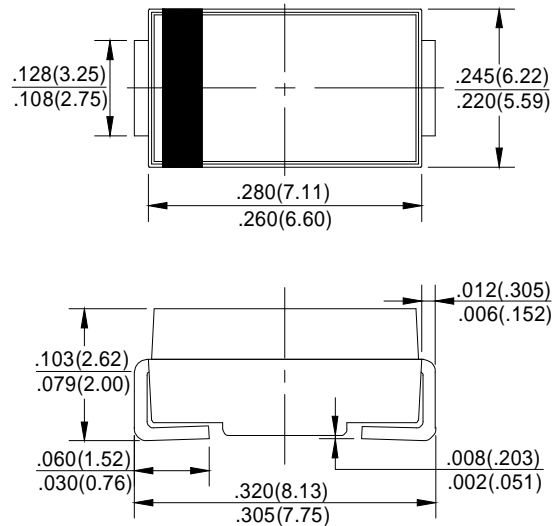
### FEATURES

- Glass passivated chip
- For surface mounted applications
- Low reverse leakage current
- Low forward voltage drop
- High current capability
- Plastic material has UL flammability classification 94V-0

### MECHANICAL DATA

- Case: Molded Plastic
- Polarity: Color band denotes cathode
- Weight: 0.007 ounces, 0.21 grams
- Mounting position: Any

**SMC**



Dimensions in inches and (millimeters)

### MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating at 25°C ambient temperature unless otherwise specified.

Single phase, half wave ,60Hz, resistive or inductive load.

For capacitive load, derate current by 20%

CHARACTERISTICS	SYMBOL	S3A	S3B	S3D	S3G	S3J	S3K	S3M	UNIT
Maximum Recurrent Peak Reverse Voltage	VRRM	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	VRMS	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	VDC	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current @TL=75 °C	I(AV)	3.0							A
Peak Forward Surge Current 8.3ms Single Half Sine-Wave Super Imposed On Rated Load (JEDEC Method)	IFSM	200							A
Maximum Forward Voltage at 3.0A DC	VF	1.2							V
Maximum DC Reverse Current @TJ=25°C at Rated DC Blocking Voltage @TJ=100°C	IR	5.0							uA
Typical Junction Capacitance (Note1)	CJ	40							pF
Typical Thermal Resistance (Note2)	RθJL	10							°C/W
Typical Thermal Resistance (Note3)	RθJA	50							°C/W
Operating Temperature Range	TJ	-55 to +150							°C
Storage Temperature Range	TSTG	-55 to +150							°C

NOTES:1.Measured at 1.0 MHz and applied reverse voltage of 4.0V DC.

2.Thermal resistance junction to lead.

3.Thermal resistance junction to ambient.

FIG. 1 - FORWARD CURRENT DERATING CURVE

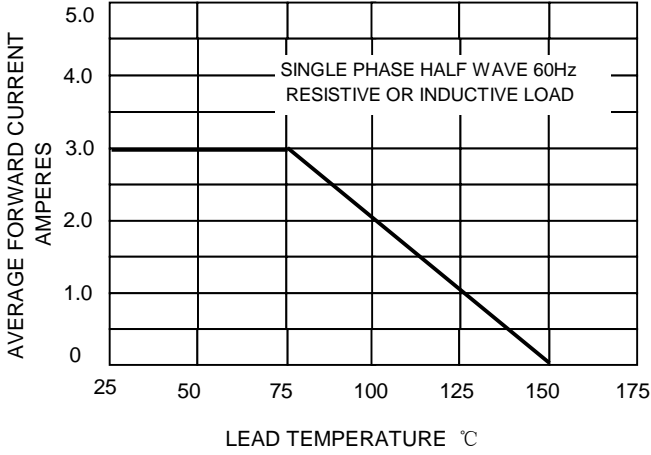


FIG. 2 - MAXIMUM NON-REPETITIVE SURGE CURRENT

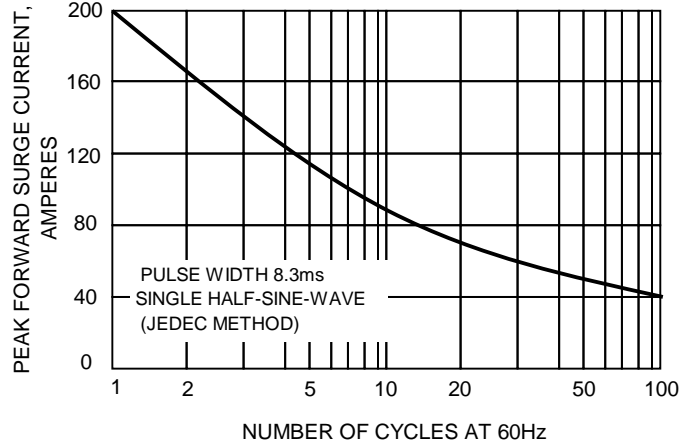


FIG. 3-TYPICAL FORWARD CHARACTERISTICS

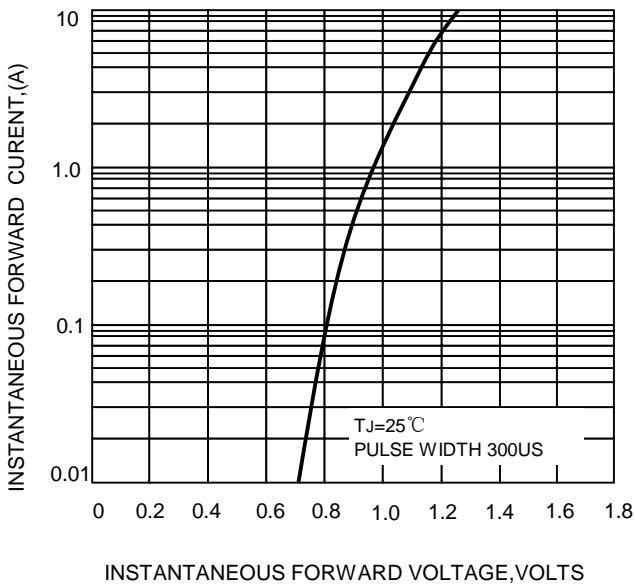


FIG. 4-TYPICAL REVERSE CHARACTERISTICS

